

# AccuScan™ Dispense

The Cee® AccuScan™ Dispense is designed for use with Apogee® Spin Coaters and Spin Developers to provide precise and uniform dispensing for semiconductor substrates. This automated dispense system enhances the efficiency and accuracy of your process, ensuring optimal performance in semiconductor fabrication.

*Serving the Semiconductor Industry Since 1987*



## SPECIFICATIONS

- Resolution: 0.1mm
- Accuracy:  $\pm 50\mu$
- Precision:  $\pm 50\mu$
- Arm speed range: 0-50mm/s
- Working Range: 0-106mm
- Max dispenses: 3 (spin) | 2 + N2 blow-off (developer)
- Max viscosity: 5,000cps (spin) | 100cps (developer)
- Max wafer thickness: 13mm (spin) | 8mm (developer)

## DESIGN

- Cleanroom compatible design
- Full programmability through DataStream™
- Drip free park position
- Acetal arm construction
- No external power supply
- Hub-less lid design

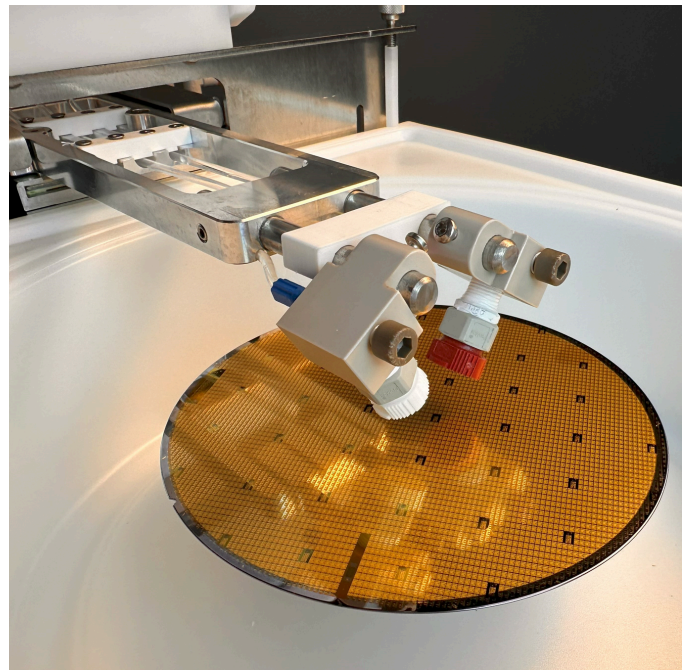
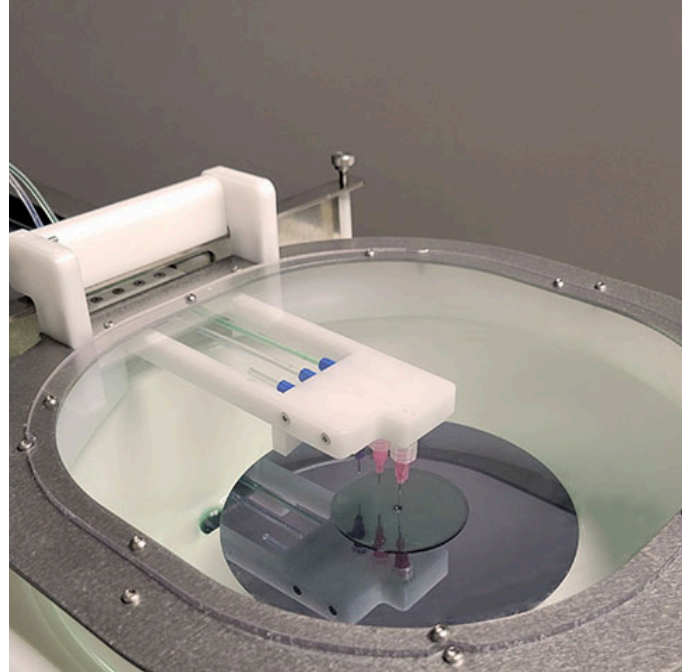
## COMPONENTS

- AccuScan™ Arm (pre-mounted)
- Stream or Spray nozzles and assorted tips

\*Dispenses and control box required, sold separately

## RELIABILITY

- Industry leading uptime
- 1-year full warranty on parts and labor
- Complimentary remote technical support for the life of the product
- Application process assistance for the life of the product



# APPLICATIONS

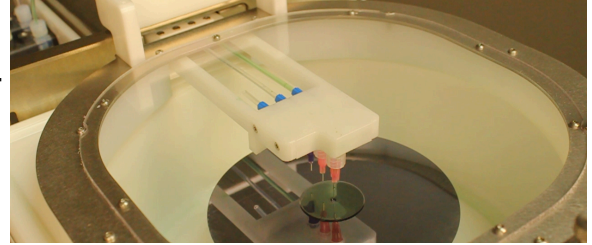
## Spin Coater

- Pre-dispense: dispense in the park position to flush nozzle before on wafer dispensing
- Standard dispense: move the nozzle to 0mm to dispense in the center of the wafer
- Offset dispense: dispense material offset from the center to leave an uncoated area in the middle of the wafer
- Scanning dispense: move the arm from center to the edge while dispensing
- Edge bead removal: precisely set the arm position to remove material at the edge of the wafer

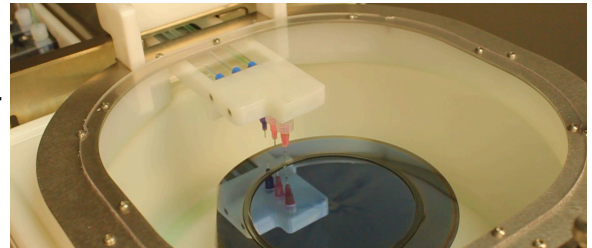
## Spin Developer/Cleaner

- High-pressure impingement spray: removes tough residues from wafer surface
- Precision dispense: recipe controlled dispense position
- Breaking surface tension - enhances liquid spread & wetting for better substrate coverage
- Metal lift-off - precisely removes unwanted metal layers
- Off-wafer pre-dispense - dispense in park position to flush nozzle before on-wafer dispense

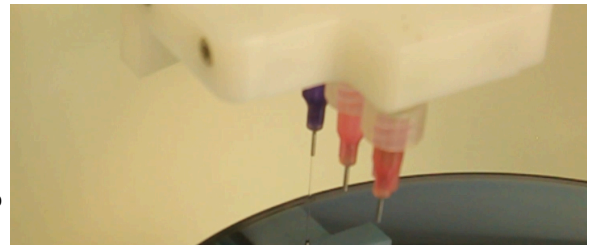
Standard Dispense



Offset Dispense

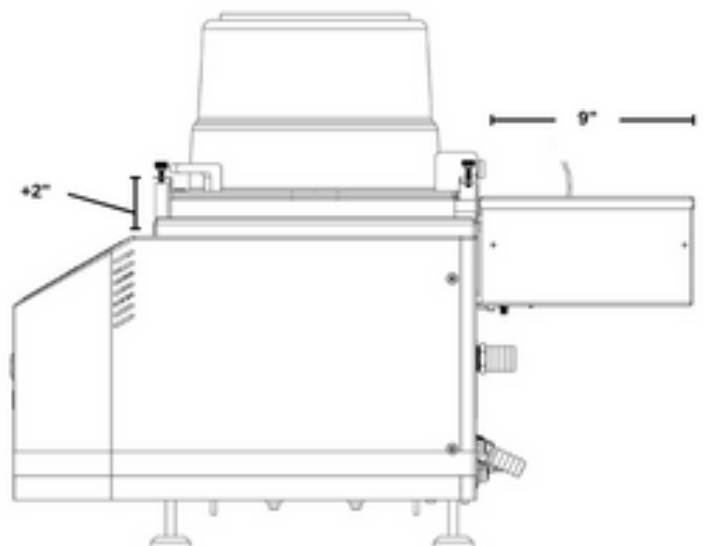
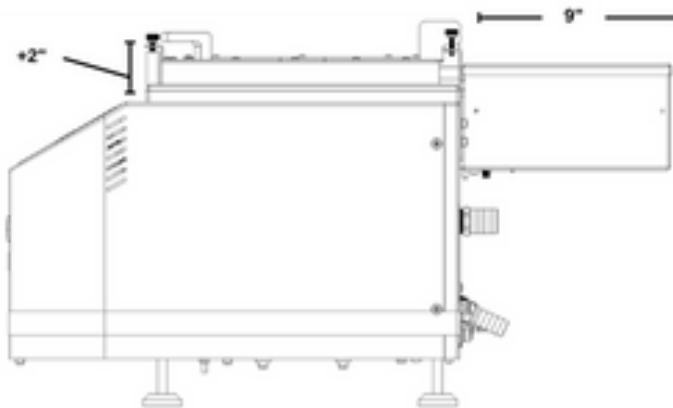


Edge Bead Removal



# DIMENSIONS

*\*adds 2" to the top and 9" to the rear of your Apogee® process module*



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Effective Date: 1/30/2024 Rev A